

FuzionXC2-60



Capacity re-defined – high-input chip solution

■ FuzionXC2-60 Platform

Universal Instruments' Fuzion™ Platform is the revolutionary foundation of a contemporary production model that maximizes productivity while reducing costs for electronics manufacturers. Fuzion features more than twice the feeder capacity of traditional placement solutions to reduce changeover requirements and optimize utilization.

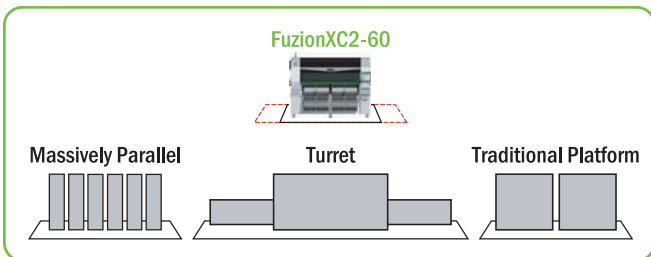
FuzionXC2-60™ is a high-speed platform within the Fuzion portfolio that extends the limitations of traditional chip solutions with larger board support and the largest on-the-fly part range. FuzionXC2-60 is a cost-efficient, high-performance turret replacement or high-input chip placer.

■ FuzionXC2-60 Advantages

- **Capacity re-defined** – 2x feeder inputs versus alternative solutions
- **Utilization and efficiency** – streamline NPI, minimize changeovers
- **All-in-one flexibility** – quote any job in an uncertain environment
- **Lowest cost of ownership** – reduced CapEx and production costs
- **Maximize floor space utilization** – replace multiple modules with a single Fuzion with more feeders

■ Capacity Re-defined

- **2x 8mm and tray feeder inputs versus alternative solutions**
- Replace multiple platforms with a single Fuzion with more feeders
- Most feeder inputs per floor space, lowest cost per input



■ Turret replacement

Optimize productivity with a dramatically reduced footprint, increased board size and part range; maximize utilization through increased feeder capacity, bank change and splice



■ High-input chip solution

Leverage twice the feeder capacity of alternative solutions to support multiple setups and alleviate changeover time; maximize utilization with a broad component range and no derate



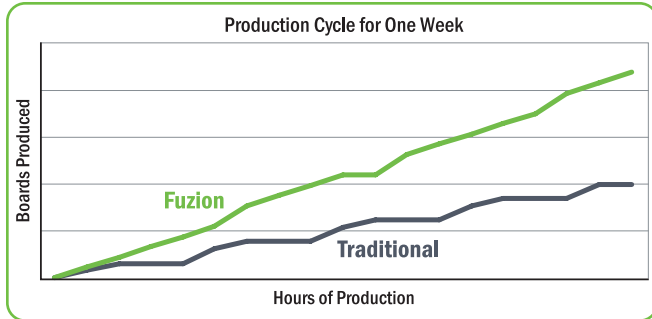
■ High-capacity complex assembly solution

Support complex, high-part count products while reducing CapEx, floor space, NPI time and maintenance



■ Optimal utilization and efficiency

- Manufacturers typically produce at very low utilization rates
- Fuzion solutions with 2x feeder capacity can boost utilization rates by 50%, resulting in a significant increase in output – enough to enable electronics manufacturers to eliminate entire production shifts
- Multiple product setups on a single platform eliminates changeovers
- Fixed family setup schemes
- Duplicate or Alternate Feeder capacity
- Feeder Anywhere – flexible feeder setup
- NPI or on-the-fly production editing accelerates ramp to volume
- Flexible, easy-loading, spliceable feeders reduce replenishment and changeover times



■ All-in-one flexibility

- Quote any product in an uncertain manufacturing environment
- Prototyping on a single platform, easily transferable to high-volume
- Broadest range of components, package types and board sizes
- Any board size – up to 1300mm x 610mm (51" x 24")
- Any component – largest on-the-fly part range of any chip placement solution with on-the-head imaging of 01005 passives to 30mm square components
- An on-line inventory of 372 nozzles eliminates the need to retool in high-mix environments

■ Lowest cost of ownership

- Reduced CapEx and overall production costs
- Fewer modules to purchase versus alternative solutions
- Less operators, training, maintenance, power/air consumption, programming and labor/repair costs



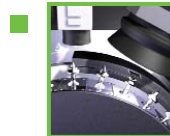
■ Positioning system

FuzionXC2-60 is built on the same solid foundation as the comprehensive Universal Instruments' surface mount platform portfolio. Patented VRM linear motor technology features a 1µm resolution, 2.5G acceleration speeds, and a dual-drive architecture for reduced settle times. VRM technology carries a 5-year warranty on Fuzion platforms.



■ Placement head technologies

FuzionXC2-60 is configured with two high-speed FZ30™ placement heads delivering the industry's fastest tact rate and a component range of 01005 passives to 30mm square for unmatched flexibility and performance.



■ Vision system

The FZ30 placement head utilizes two on-the-head vision systems to image the full range of 01005 passives to 30mm square components on-the-fly.

- Narrow field of view to image 01005 to 12mm square
- Configurable wide field of view to image up to 30mm square
- Images lead-less, leaded, bumped, and odd-form components
- On-the-head Vertical Part Sensor assures part presence/orientation

■ Vertical Part Sensor (VPS)

- Images components from a side angle prior to placement
- Detects part presence from 01005 to 30mm square components
- Measures component height or vertical orientation for 01005 to 0603 passive components up to 1.27mm tall
- Inspects nozzles and enables on-the-fly exchange of suspect nozzles

■ Optimal small part performance

- Auto Pocket Teach assures successful first pick
- Auto X, Y Pick Update automatically tunes feeder pick point
- Lightning Head single pick point eliminates gang picking concerns
- Touchdown Sense determines impact heights at both pick and place
- Auto Z Update at Pick compensates for varying pick heights
- Auto Z Update at Place guarantees ideal placement force



■ Common peripherals

FuzionXC2-60 retains peripheral compatibility with all Advantis 3 and Genesis Series 2 Platforms, and many older vintage models.

FUZIONXC2-60 SPECIFICATIONS

Placement Rate (cph (sec per comp))	Max	65,500 (0.055)
	1-Bd IPC Chips (I608)	30,000 (0.120)
Accuracy (µm@1.33 Cpk/1.00 Cpk)	Chips, ICs	±55 / ±41
	PCB Dimensions (mm("))	Max (WxL)
Component Range (mm ("))	Min (WxLxH)	50.8 x 50.8 x 0.508 (2 x 2 x 0.02)
	Max Weight (kg (lbs))	5.0 (11.0)
Machine Dimensions (mm("))	Max (WxLxH)	30 x 30 x 6 ² (1.18 x 1.18 x 0.24)
	Min (WxLxH)	0.18 x 0.38 x 0.10 (0.007 x 0.015 x 0.004)
Feeder Inputs	(LxDxH)	2385 x 2160 x 1930 (93.90 x 85.04 x 75.90)
		Up to 264 8mm inputs – types: tape, strip, tray

¹ Optional Long Board Kit required

² Consult the General Specification for component capability specifics